



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	03/11/2015
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	Group MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	BA3E*D80F8AQ	A	Z6IA	03/11/2015
Amount	UoM	Unit type	ST ECOPACK Grade	
26.40	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFF	1.75X4.7X0.98	N/A	flat	
Comment	Package: SOD128-FLAT NEP; MD valid for STTH3R02AFY			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

ELV exemption number	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Exemption Id.	Description
	#N/A
	#N/A

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BA3E*D80F8AQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.832	mg	supplier	Silicon die	Silicon	7440-21-3		1.095	mg	947232	41477
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	25087	1098
				supplier	passivation	Silicon Nitride (SiN)	12033-89-5		0.007	mg	6055	265
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.010	mg	8651	379
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	1730	76
				supplier	back side metallization	Gold (Au)	7440-57-5		0.003	mg	2595	114
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	8651	379
Leadframe	Copper and its alloys	9.805	mg	supplier	Leadframe	Copper	7440-50-8		9.466	mg	998460	358561
				supplier	Leadframe	Iron	7439-89-6		0.011	mg	1181	424
				supplier	Leadframe	Iron Phosphide (Fe2P)	1310-43-6		0.003	mg	359	129
Leadframe clip	Copper and its alloys	2.525	mg	supplier	Leadframe Clip	Copper	7440-50-8		2.462	mg	974932	93250
				supplier	Leadframe Clip	Iron	7439-89-6		0.059	mg	23484	2246
				supplier	Leadframe Clip	Zinc	7440-66-6		0.003	mg	1188	114
				supplier	Leadframe Clip	Iron Phosphide (Fe2P)	1310-43-6		0.001	mg	396	38
Die Attach	Other organic materials	2.749	mg	JIG R	Solder Paste	Lead	7439-92-1	7a-Lead in high me	2.612	mg	950164	98939
				supplier	Solder Paste	Tin	7440-31-5		0.137	mg	49836	5189
Encapsulation	Other organic materials	10.194	mg	supplier	Molding Compound	Silica	60676-86-0		6.242	mg	612374	236451
				supplier	Molding Compound	Epoxy Cresol Novolak	29690-82-2		1.679	mg	164711	63598
				supplier	Molding Compound	Metal hydroxide	Proprietary		1.343	mg	131769	50879
				supplier	Molding Compound	Phenol resin	9003-35-4		0.896	mg	87849	33920
				supplier	Molding Compound	carbon black	1333-86-4		0.034	mg	3296	1273
Connection coating	Other inorganic materials	0.295	mg	supplier	Solder Alloy	Tin	7440-31-5		0.295	mg	1000000	11182